IEEE COINS 2023

IEEE International Conference on Omni-layer Intelligent Systems

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Berlin, Germany | Hybrid
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Call for Papers

Track Name: EDA for AI, IoT, and Cyber-physical Systems

Electronic Design Automation (EDA) ecosystem plays a crucial role in the development of intelligent solutions: from connected IoT Edge devices to large scale Autonomous Systems. At the same time, Artificial Intelligence is being incorporated into EDA tools and processes to speed-up design and improve designed systems' quality.

The EDA track of IEEE COINS provides a central location for all members of the ecosystem to connect, share, learn and witness cutting edge research in all areas of development for EDA in IoT and Intelligent Systems, and for the application of Artificial Intelligence to EDA. This track encourages original and high-quality submissions related to one or more of the following topics (but not limited to):

EDA for Intelligent and Autonomous Systems

- System Design, High-Level Synthesis and Optimization
- Design Methodologies for Machine Learning Architectures
- Specification and Modeling Languages for Intelligent Systems
- Formal Methods and System Verification
- CAD for Cyber-Physical Systems

Artificial Intelligence Applications to EDA

- Artificial Intelligence Applications to IC Design and VLSI
- Artificial Intelligence Applications to Cyber-Physical Systems Design
- Artificial Intelligence for System Simulation, Verification and Testing

EDA for IoT, Edge and Cloud Computing Systems Design

- Device Modeling, System Simulation and Validation
- Temperature and Variability Aware Design and Optimization
- Power Modeling, Optimization and Low-Power Design

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